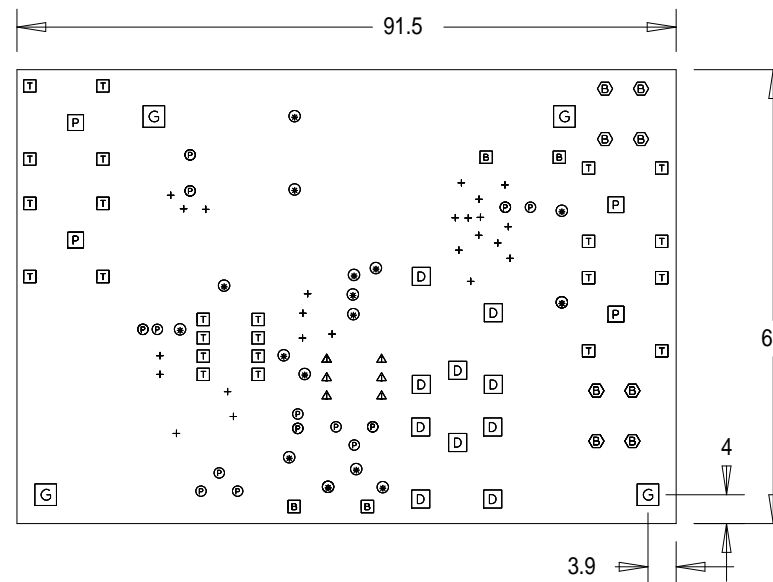


SPEC:

COMPLIANT RoHS DIRECTIVE 2011/65/UE


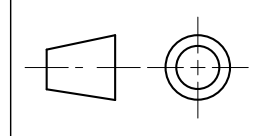
MATERIAL	FR4 IMPROVED (low CTE)		
BOARD THICKNESS		1.6mm /63mils	
STACKUP	DF /2LAYERS		
MINIMAL GAP		210um /8.0mils	
MINIMAL SLIVER		210um /8.0mils	
COPPER THICKNESS		35um(1oz)at START	
FINISH THICKNESS	CHEMICAL NiAu		
SOLDER MASK		GREEN TOP & BOT	
SILKSCREEN	WHITE TOP		
ALL BOARD ELECTRICALLY TESTED			
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK			



DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILLIMETERS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
+	0.5 VIA	+0.0/-0.0	PLATED	24
⊙	0.8	+0.1/-0.05	PLATED	14
△	0.9	+0.1/-0.05	PLATED	6
⊙	1.0	+0.1/-0.05	PLATED	16
⊙	1.1	+0.1/-0.05	PLATED	4
⊙	1.4	+0.1/-0.05	PLATED	24
⊙	2.0	+0.1/-0.05	PLATED	8
P	2.2	+0.1/-0.05	PLATED	4
D	2.25	+0.05/-0.05	PLATED	10
G	3.0	+0.1/-0.1	NON-PLATED	4

1.0		W34/2018
indice	Description	Date
Controle par :		Autorise par:
 ON semiconductor		Definition CUT DRILL DRAWING PLAN PRECAGE DETOURAGE 
Board: VM BUCK UC384x EVB-A-TLS		Subc. DYPE TECH Dessine: e B Echelle: 1/1
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